US00D628170S

(12) **United States Design Patent**
Maruyama et al.

(10) **Patent No.: US D628,170 S**
(45) **Date of Patent: ** *Nov. 30, 2010**

(54) **SEMICONDUCTOR WAFER PROCESSING TAPE**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

(21) Appl. No.: **29/321,421**

(22) Filed: **Jul. 16, 2008**

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** .... D13/182; 156/235, 248; 428/343, 345, 353, 355 R; 438/114, 455, 460, 463
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a "semiconductor wafer processing tape," as shown and described.

DESCRIPTION

FIG. **1** is a perspective view showing our new design;

FIG. **2** is a top plan view;

FIG. **3** is a bottom plan view;

FIG. **4** is a left side view;

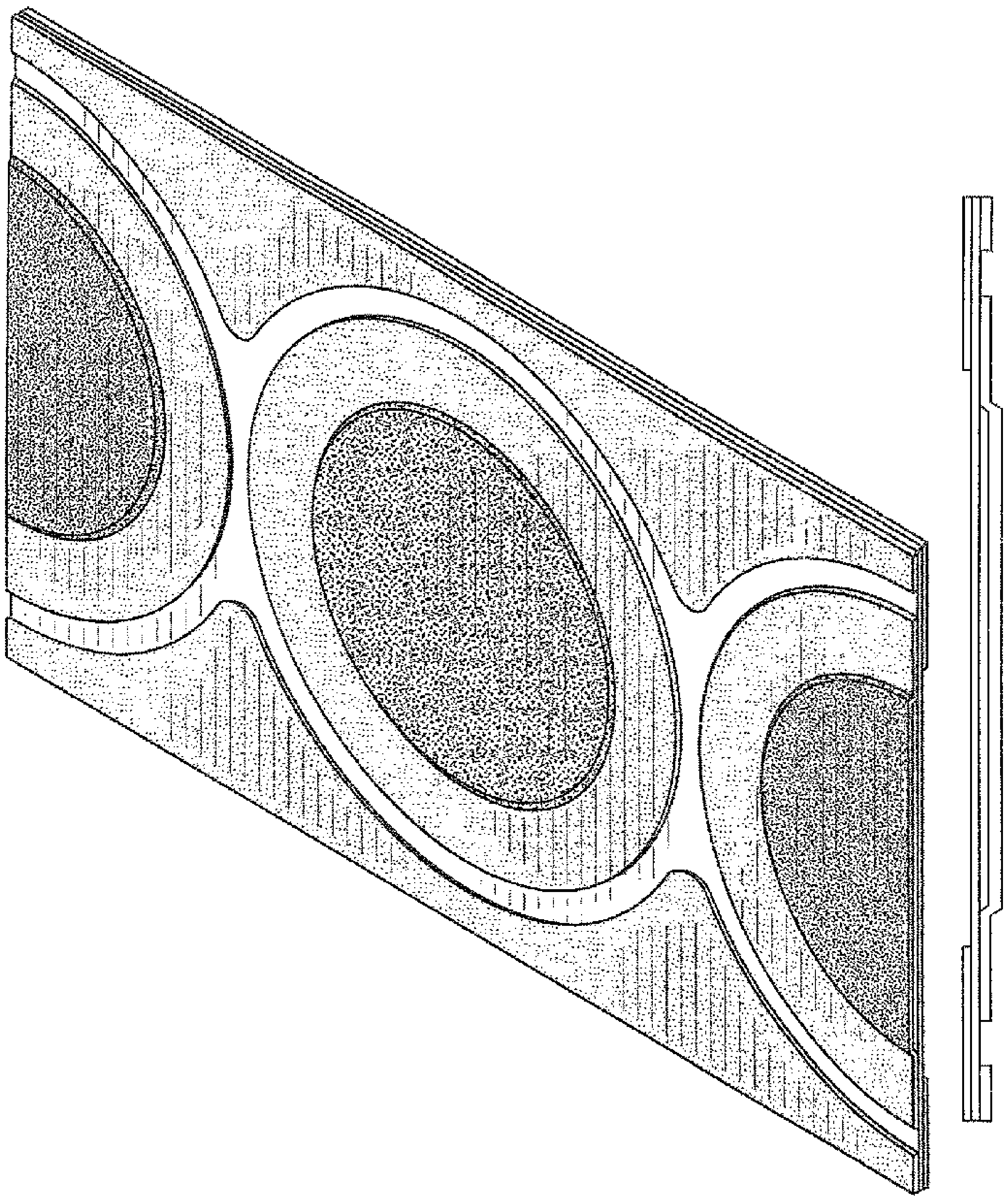
FIG. **5** is a front side view;

FIG. **6** is a right side view;

FIG. **7** is a cross sectional view at **7**—**7** of FIG. **1**; and,

FIG. **8** is a cross sectional view at **8**—**8** of FIG. **1**.

1 Claim, 5 Drawing Sheets



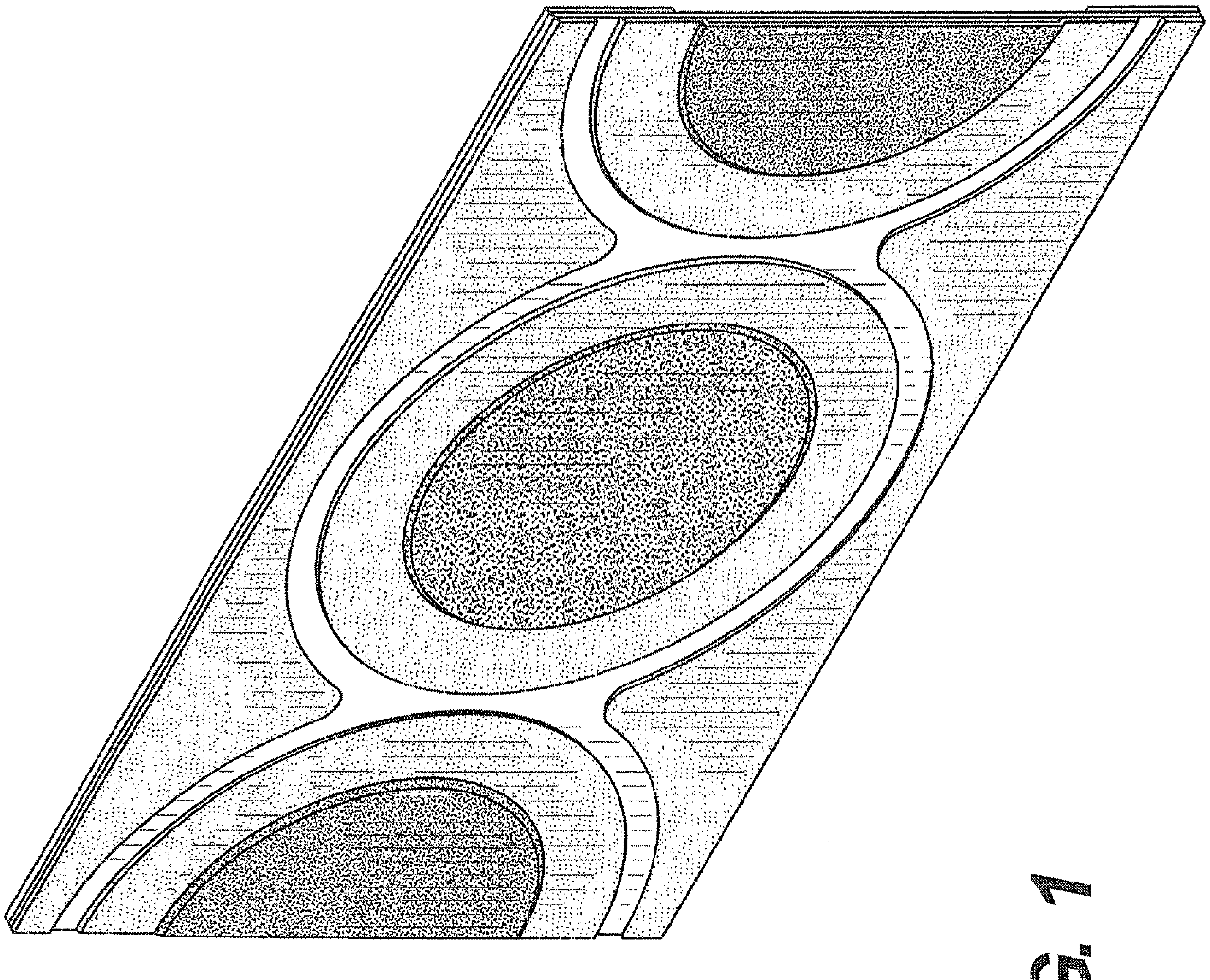


FIG. 1

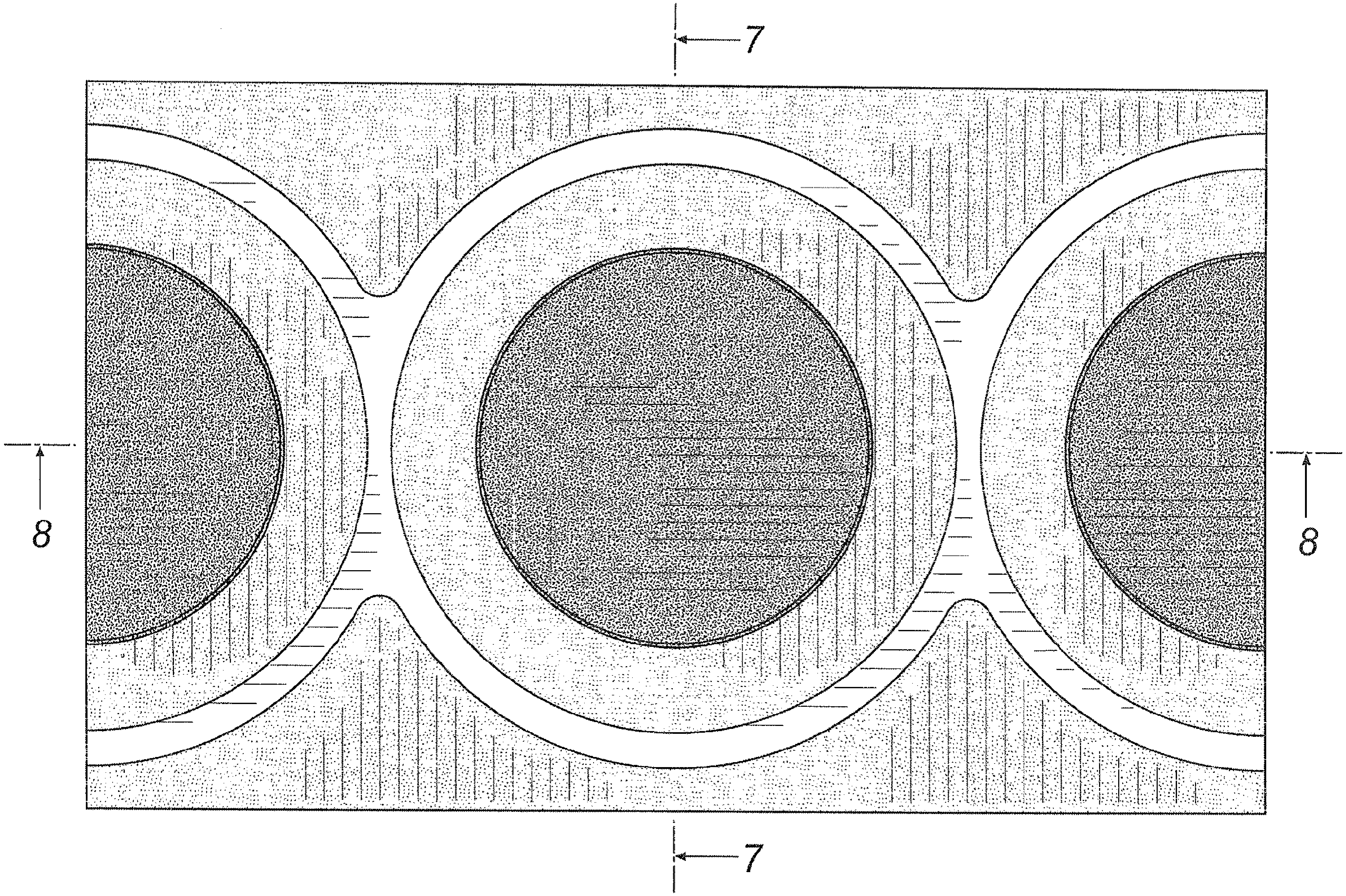


FIG. 2

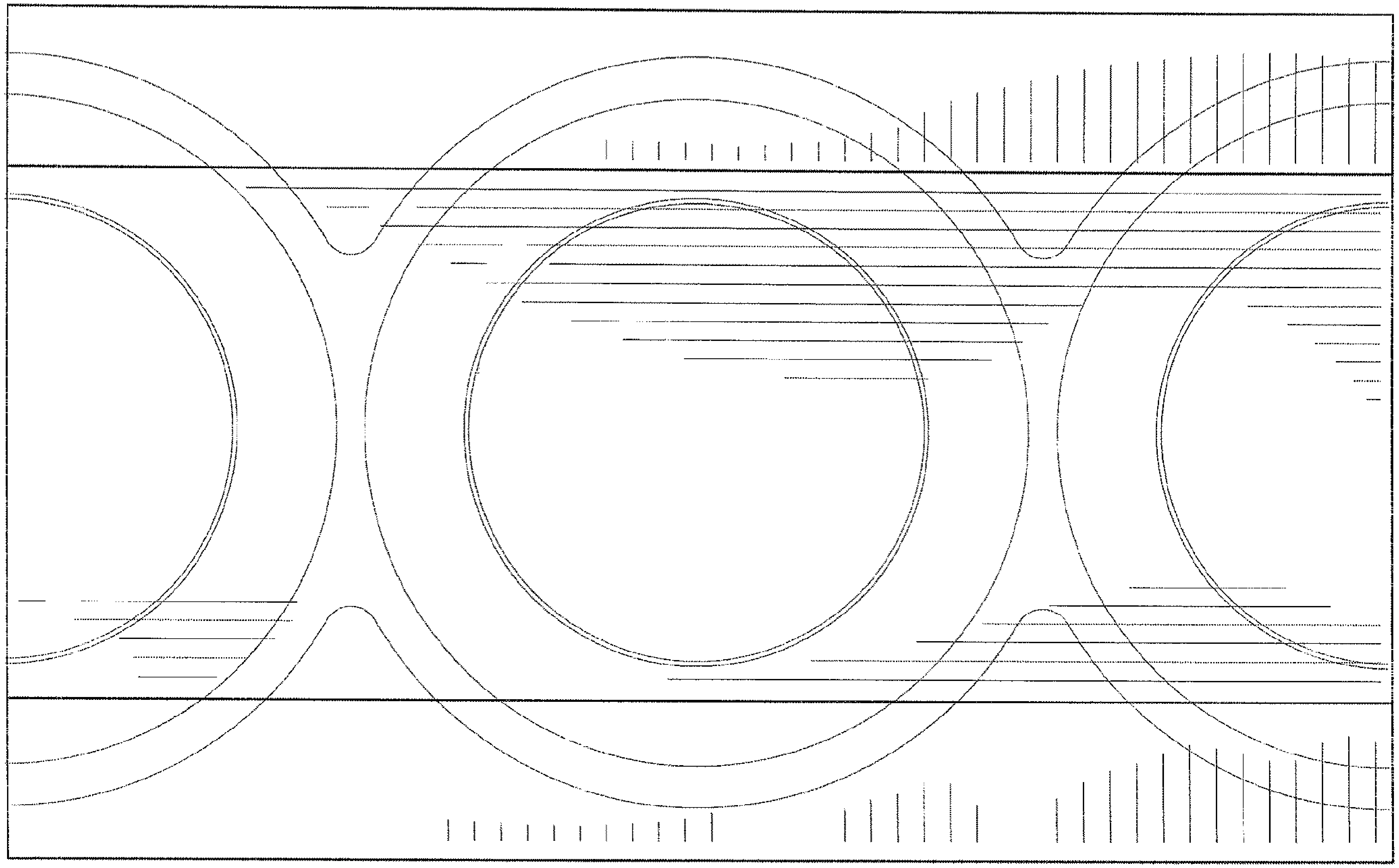


FIG. 3

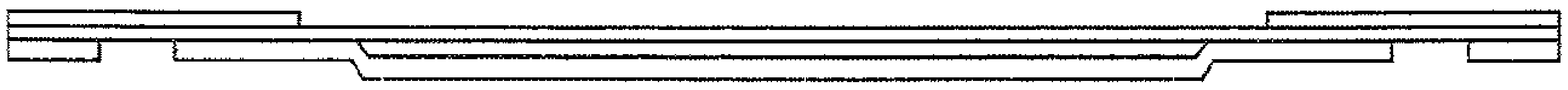


FIG. 6

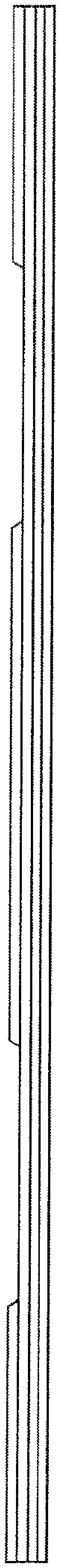


FIG. 5

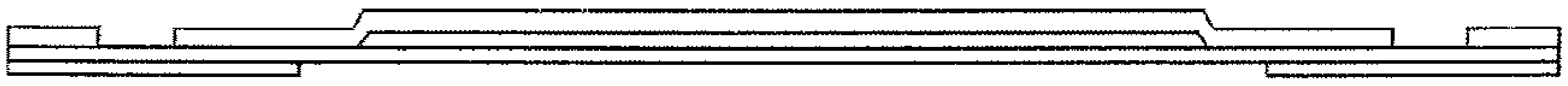


FIG. 4

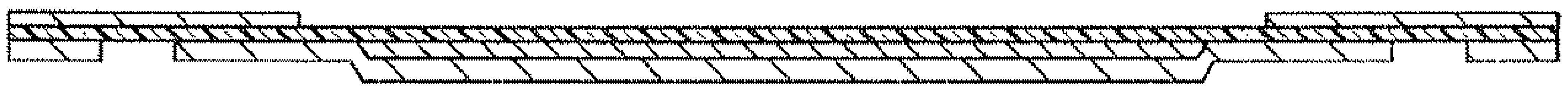


FIG. 7

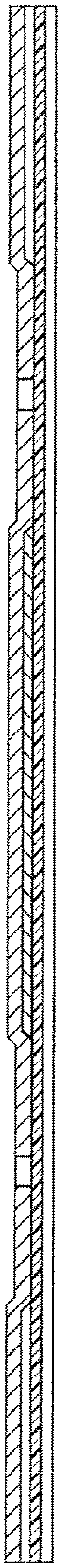


FIG. 8